

SFPG-8 Solvent Free Prepreg Glass-Fiber Reinforced

Item	Thickness	Unit	Value (Typ.)	Method
Thermal Pro	perties			
Product Thermal C	Conductivity	W/m-K	7.6 *	TO-220
Dielectric Thermal	Conductivity	W/m-K	1.85	ASTM D5470
Thermal Resistance 100µm (4mil)		°C/W	<0.09	ASTM D5470
Thermal Impedance 100µm (4mil)		°C/W	0.09	TO-220
Electrical Properties				
Dielectric Constan	t	-	6.1	IPC-TM-650 2.5.5.9
Dissipation Factor	I 00μm (4mil)	IMHz	0.016	IPC-TM-650 2.5.5.9
Capacitance	I 00μm (4mil)	pF	20.8	IPC-TM-650 2.5.5.9
Volume Resistivity		Ω-cm	1013	IPC-TM-650 2.5.17.1
Surface Resistivity		Ω/sq	10 ¹⁵	IPC-TM-650 2.5.17.1
Breakdown Voltage	9	KVAC	>30	ASTM D149
Mechanical Properties				
Color		-	Off-White	Visual
Peel Strength @ 25	5°C	Kg/cm (lbf/in)	1.4 (7.8)	IPC TM-650 2.4.8
Glass Transition (T	-g)	°C	150	IPC TM-650 2.4.25
CTE in X,Y/Z Axis	<tg< td=""><td>μm/m°C</td><td>28</td><td>IPC TM-650 2.4.25</td></tg<>	μm/m°C	28	IPC TM-650 2.4.25
CTE in X,Y/Z Axis	>Tg	μm/m°C	35	IPC TM-650 2.4.25
Youngs Modulus		GPa	30	ASTM D638
Chemical Properties				
Water Vapor Rete	ntion	%	< 0.5	ASTM E595
Out-Gassing Total Mass Loss		%	< 0.1	ASTM E595
Collect Volatile Co Material	ondensable	%	< 0.1	ASTM E595
Agency Ratings & Durability- UL: E121882				

Features & Benefits

- SFPG-8 (Solvent Free Prepreg Glass-Fiber Reinforced) provides the advantage of high thermal conductivity and reliability. This Sem-finished material is good for single and multilayer thermal conductive printed circuit board applications.
- SFPG-8 is a sandwich structure, which includes layers of upper release film, prepreg, and lower release film
- SFPG-8 has one layer of fiberglass which allows adequate strength to be able to do two-sided etching with thin core material.
- Excellent thermal conductivity
- High Electrical Strength
- Lead-free solder compatible
- · RoHS compliant and environmentally green
- · Available in rolls
- TCLAD SFPG-8 minimizes thermal impedance and conducts heat more efficiently than standard printed wiring boards (PWB's).
- The differentiating technology of Thermal Clad resides in the dielectric. This
 datasheet highlights the performance characteristics of TCLAD SFPG-8.
- *Product thermal conductivity based on 2oz cu x 100µm SFLG-8 x 1.5mm Al

Applications

- Traditional multilayer PCBs that have hot spots that needs to be dissipated
- High power density applications which required low thermal resistance
- Power conversion, Inverter, DC/DC, AC/DC
- Industrial motor drives
- Solid State Relays

Configurations

Roll width [mm]

Droprog Thickness

Prepreg Thickness [μm]

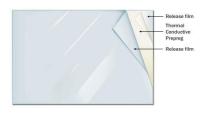
Release Film Thickness [µm]

SFPG-8

510,520 etc.

50,80,100,150 etc.

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We provide custom solutions for your applications. For Further questions, please contact your local sales agent or directly TCLAD sales in your region.

Test Thermal Performance of Insulated Metal Substrate (IMS®) TO-220 Set-up



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UL Flammability

RoHS

compliant

V-0